

SOT2113-1

VFBGA120, very thin fine pitch ball grid array package, 120 terminals, 0.5 mm pitch, 7 mm x 7 mm x 0.87 mm body

11 December 2020

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	VFBGA120
Package style descriptive code	VFBGA (very thin fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	12-10-2020
Manufacturer package code	98ASA01719D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	6.9	7	7.1	mm
package width	6.9	7	7.1	mm
package height	-	0.87	1	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	120	-	



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2 Package outline

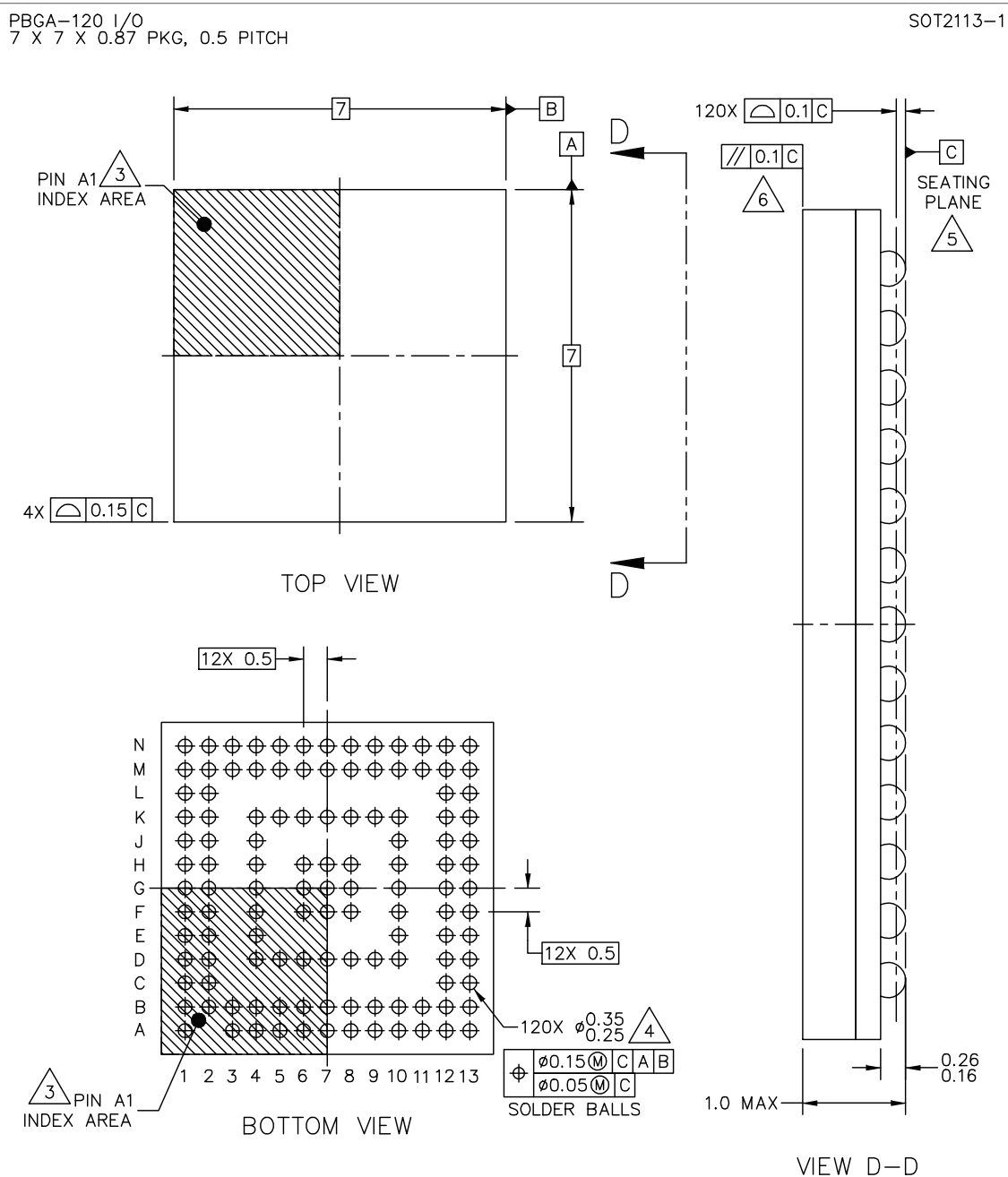
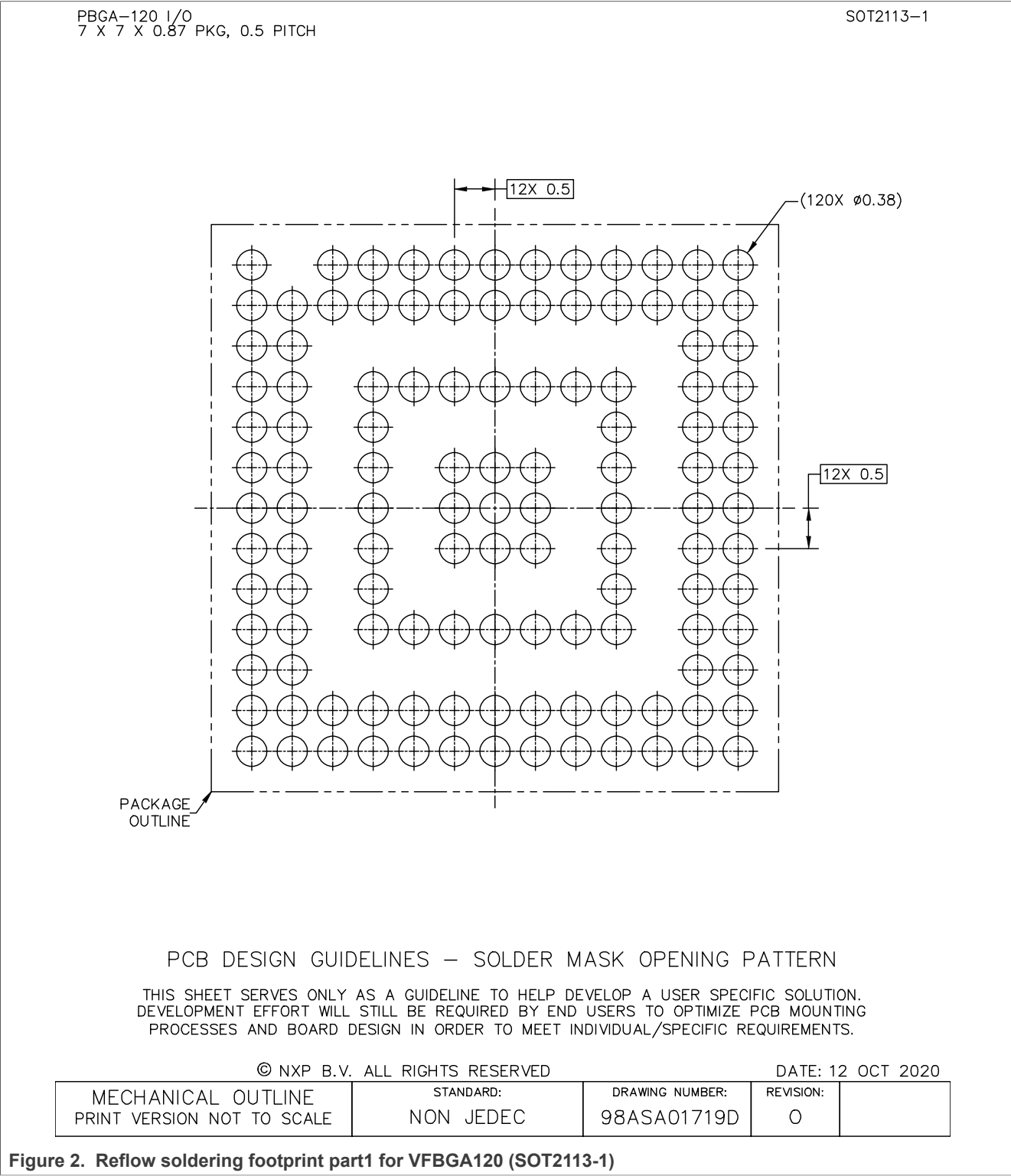


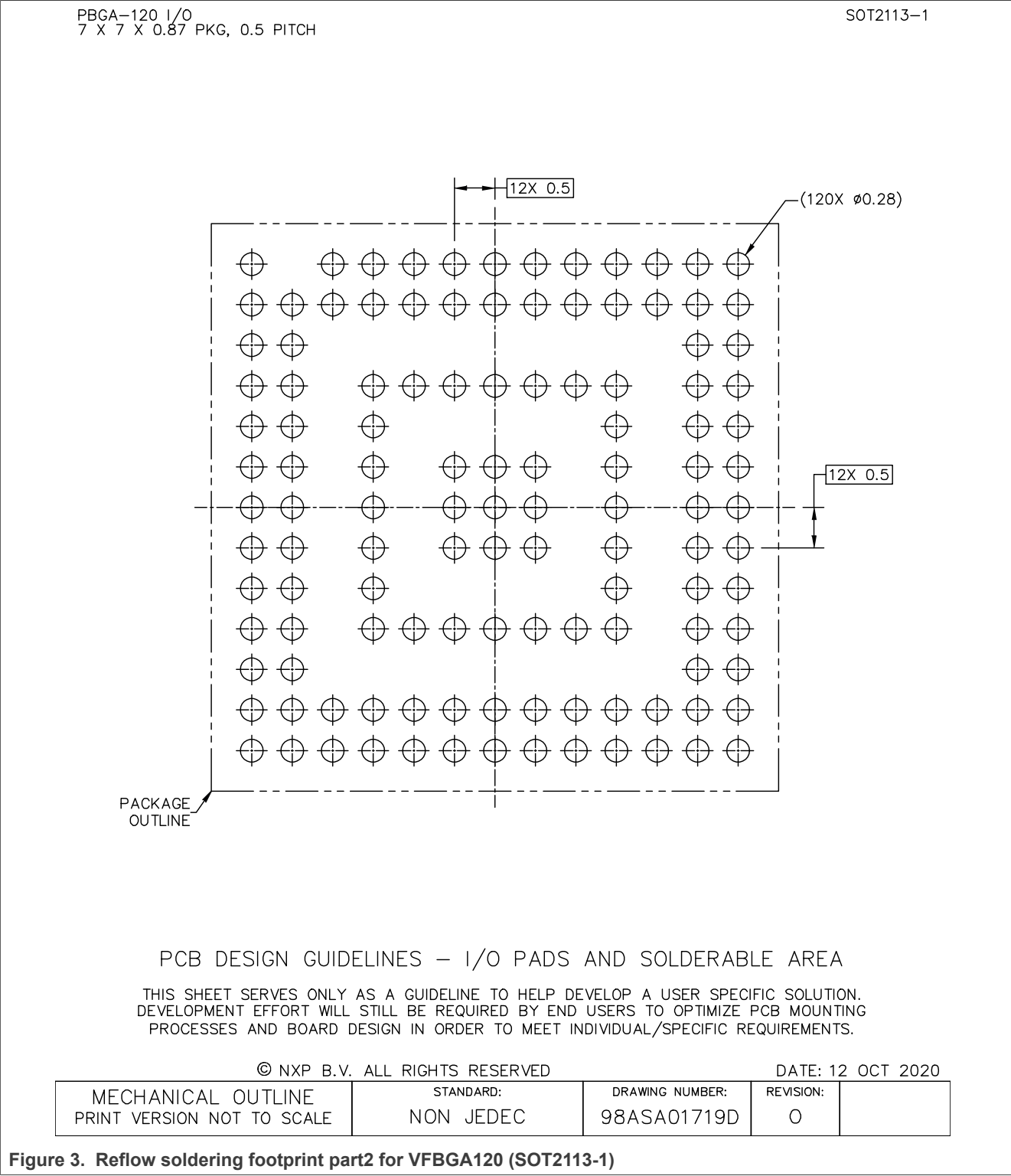
Figure 1. Package outline VFBGA120 (SOT2113-1)

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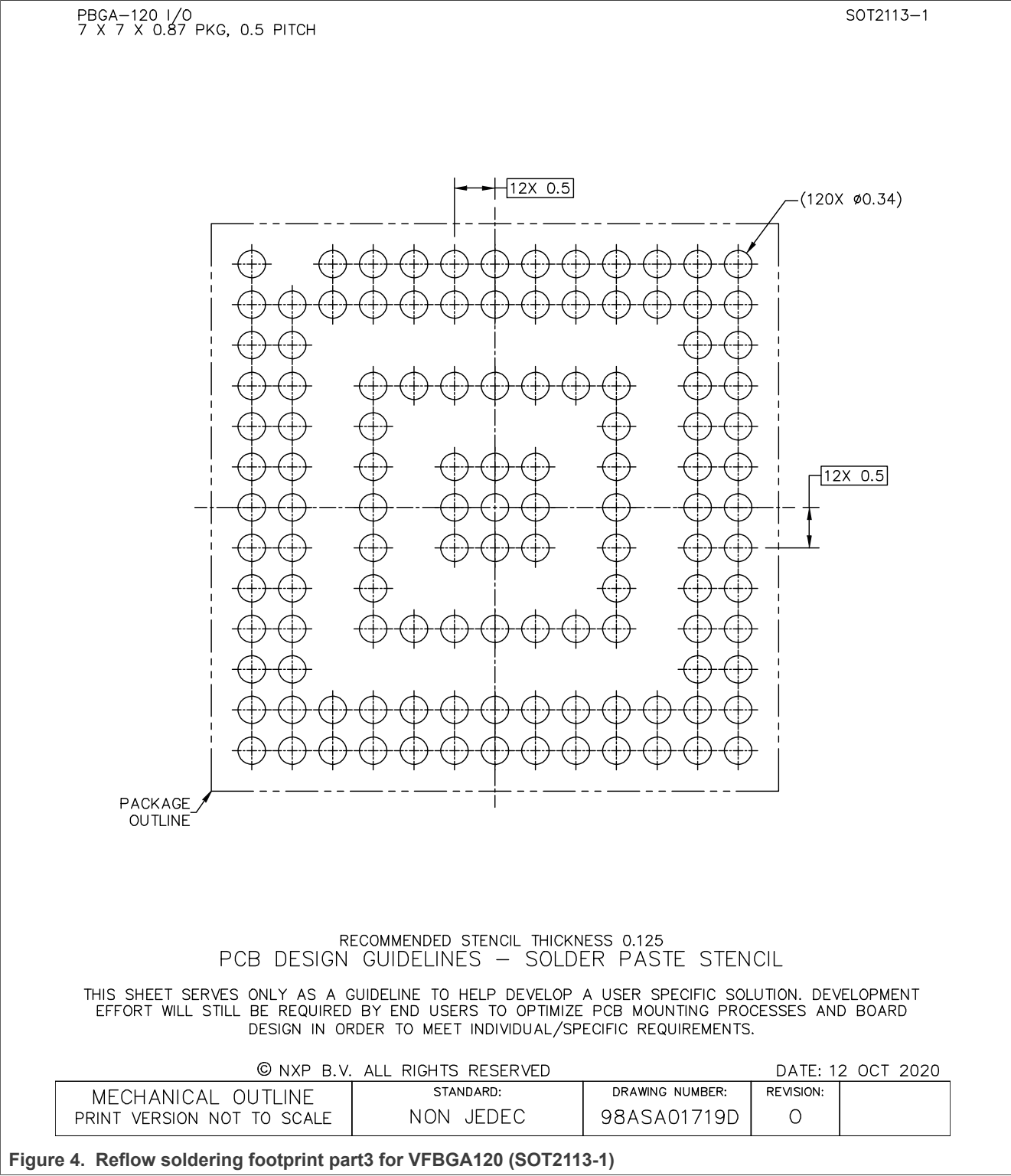
3 Soldering



VFBGA120, very thin fine pitch ball grid array package, 120 terminals, 0.5 mm pitch, 7 mm x 7 mm x 0.87 mm body



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PBGA-120 I/O
7 X 7 X 0.87 PKG, 0.5 PITCH

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NOTES:

- 1. ALL DIMENSIONS IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
- 4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
- 5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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DATE: 12 OCT 2020

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01719D	REVISION: O	
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Figure 5. Package outline note VFBGA120 (SOT2113-1)

4 Legal information

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